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## Materials Declaration Form

<b>IPC Form Type *</b>	<b>1752</b> Distribute	<b>Version</b>	<b>2</b>
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2016-03-10</b>
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Antonella Lanzafame	<b>Representative Title</b>	AMS & IPD Materials Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

Uncertainty Statement	
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Legal Statement	
<b>Supplier Acceptance *</b>	<b>true</b>
<b>Legal Declaration *</b>	<b>Standard</b>
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	7N6U*228J83Y	A	Z8GA	2016-03-10
Amount	UoM	Unit type	ST ECOPACK Grade	
330.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	6.5X6.1X2.3	2	gull wing	
Comment	TO 252 DPAK, MD valid for CP:STPS1L30MF.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	7N6U*228J83Y					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
SILICON DIE	Other inorganic materials	0.877	mg	supplier	DIE	Silicon (Si)	7440-21-3		0.816	mg	930445	2473
SILICON DIE				supplier	METALLIZATION	Aluminium (Al)	7429-90-5		0.039	mg	44470	118
SILICON DIE				supplier	METALLIZATION	Titanium (Ti)	7440-32-6		0.001	mg	1140	3
SILICON DIE				supplier	METALLIZATION	Titanium Nitride (TiN)	25583-20-4		0.001	mg	1140	3
SILICON DIE				supplier	BACK SIDE METALLIZATION	Tungsten (W)	7440-33-7		0.001	mg	1140	3
SILICON DIE				supplier	BACK SIDE METALLIZATION	Nickel (Ni)	7440-02-0		0.001	mg	1140	3
SILICON DIE				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.006	mg	6842	18
SILICON DIE				supplier	passivation	Durimide	proprietary		0.012	mg	13683	36
Leadframe	Copper and its alloy	168.062	mg	Supplier	Alloy	Copper(CU)	7440-50-8		167.809	mg	998495	508512
Leadframe				Supplier	Alloy	Iron(Fe)	7439-89-6		0.202	mg	1202	612
Leadframe				Supplier	Alloy	Phosphorus(P)	7723-14-0		0.051	mg	303	155
Die Attach	Other Organic Material	2.082	mg	Supplier	Soft Solder	Tin(Sn)	7440-31-5		0.042	mg	20173	127
Die Attach				Supplier	Soft Solder	Silver(Ag)	7440-22-4		0.052	mg	24976	158
Die Attach				Supplier	Soft Solder	Lead	7439-92-1	7a-Lead in high me	1.988	mg	954851	6024
Bonding wire	Other Inorganic Material	1.559	mg	Supplier	Bonding wire	Aluminum(Al)	84195-93-7		1.559	mg	1000000	4724
Encapsulation	Other Organic Material	154.693	mg	Supplier	Molding compound	Epoxy Resin A	proprietary		6.188	mg	40002	18752
Encapsulation				Supplier	Molding compound	Epoxy Resin B	proprietary		6.188	mg	40002	18752
Encapsulation				Supplier	Molding compound	Phenol Resin	29690-82-2		6.188	mg	40002	18752
Encapsulation				Supplier	Molding compound	Silica(Amorphous) A	60676-86-0		123.754	mg	799997	375012
Encapsulation				Supplier	Molding compound	Silica(Amorphous) B	7631-86-9		11.602	mg	75000	35158
Encapsulation				Supplier	Molding compound	Carbon Black	1333-86-4		0.773	mg	4997	2342
Finishing	Other Inorganic Material	2.727	mg	Supplier	Connection Coating	Tin(Sn)	7440-31-5		2.727	mg	1000000	8264